

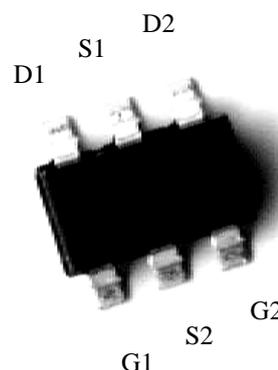
N- AND P-Channel Enhancement Mode MOSFET

Features:

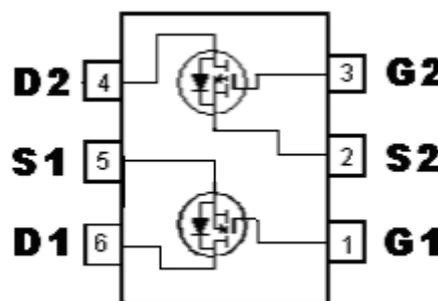
- Simple drive requirement
- Low gate charge
- Low on-resistance
- Fast switching speed
- Pb-free package

Outline

TSOP-6



Equivalent Circuit



G : Gate
 S : Source
 D : Drain

	N-CH	P-CH
BV _{DSS}	100V	-100V
I _D	1.4A (V _{GS} =10V)	-1.1A (V _{GS} =-10 V)
R _{DS(on)(TYP.)}	280mΩ (V _{GS} =10V)	450mΩ (V _{GS} =-10V)
	295mΩ (V _{GS} =4.5V)	500mΩ (V _{GS} =-4.5V)

Ordering Information

Device	Package	Shipping
KWC8959G6	TSOP-6 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits		Unit	
		N-channel	P-channel		
Drain-Source Breakdown Voltage	BV _{DSS}	100	-100	V	
Gate-Source Voltage	V _{GS}	±20	±20	V	
Continuous Drain Current (Note 1)	T _A =25°C, V _{GS} =10V(N-CH), V _{GS} =-10V(P-CH)	I _D	1.4	-1.1	A
	T _A =70°C, V _{GS} =10V(N-CH), V _{GS} =-10V(P-CH)	I _D	1.1	-0.88	A
Pulsed Drain Current (Note 2)	I _{DM}	5.6	-4.4	A	
Total Power Dissipation (Note 1) Linear Derating Factor	P _d	1.25		W	
		0.01		W / °C	
Operating Junction and Storage Temperature	T _j , T _{stg}	-55~+150		°C	
Thermal Resistance, Junction-to-Ambient (Note 1)	R _{th,ja}	100		°C/W	

Note : 1.Surface mounted on 1 in² copper pad of FR-4 board, t≤5 sec; 180°C/W when mounted on minimum copper pad
 2.Pulse width limited by maximum junction temperature

N-Channel Electrical Characteristics (T_j=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	100	-	-	V	V _{GS} =0V, I _D =250μA
V _{GS(th)}	1	1.9	2.5	V	V _{DS} =V _{GS} , I _D =250μA
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0V
I _{DSS}	-	-	1	μA	V _{DS} =80V, V _{GS} =0V
I _{DSS}	-	-	10	μA	V _{DS} =80V, V _{GS} =0V, T _j =70°C
*R _{Ds(ON)}	-	280	420	mΩ	V _{GS} =10V, I _D =1.4A
	-	295	450		V _{GS} =4.5V, I _D =1A
*G _{FS}	-	2.5	-	S	V _{DS} =10V, I _D =1.4A
Dynamic					
C _{iss}	-	545	-	pF	V _{DS} =30V, V _{GS} =0V, f=1MHz
C _{oss}	-	14	-		
C _{rss}	-	11	-		
*t _{d(ON)}	-	9	-	ns	V _{DS} =50V, I _D =1A, V _{GS} =10V, R _G =10Ω
*t _r	-	26	-		
*t _{d(OFF)}	-	39	-		
*t _f	-	9	-		
*Q _g	-	6.8	-	nC	V _{DS} =50V, I _D =1.4A, V _{GS} =10V
*Q _{gs}	-	1.4	-		
*Q _{gd}	-	2.4	-		
Source-Drain Diode					
*V _{SD}	-	0.77	1.2	V	V _{GS} =0V, I _S =1A
*t _{rr}	-	15	-	ns	I _F =1A, V _{GS} =0V, dI _F /dt=100A/μs
*Q _{rr}	-	8	-	nC	

*Pulse Test : Pulse Width ≤300μs, Duty Cycle ≤2%

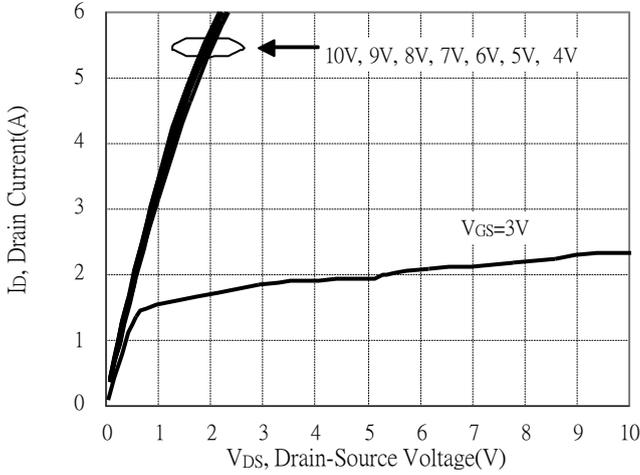
P-Channel Electrical Characteristics (T_j=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-100	-	-	V	V _{GS} =0V, I _D =-250μA
V _{GS(th)}	-1.0	-1.9	-2.5	V	V _{DS} =V _{GS} , I _D =-250μA
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0V
I _{DSS}	-	-	-1	μA	V _{DS} =-80V, V _{GS} =0V
I _{DSS}	-	-	-10	μA	V _{DS} =-80V, V _{GS} =0V, T _j =70°C
*R _{DS(ON)}	-	450	600	mΩ	V _{GS} =-10V, I _D =-0.6A
	-	500	700		V _{GS} =-4.5V, I _D =-0.4A
*G _{FS}	-	1.8	-	S	V _{DS} =-10V, I _D =-0.6A
Dynamic					
C _{iss}	-	516	-	pF	V _{DS} =-30V, V _{GS} =0V, f=1MHz
C _{oss}	-	16	-		
C _{rss}	-	12	-		
*t _{d(ON)}	-	9	-	ns	V _{DS} =-50V, I _D =-1A, V _{GS} =-10V, R _G =10Ω
*t _r	-	26	-		
*t _{d(OFF)}	-	36	-		
*t _f	-	9	-		
*Q _g	-	6.5	-	nC	V _{DS} =-50V, I _D =-1.1A, V _{GS} =-10V
*Q _{gs}	-	1.2	-		
*Q _{gd}	-	2.4	-		
Source-Drain Diode					
*V _{SD}	-	-0.81	-1.2	V	V _{GS} =0V, I _S =-1A
*t _{rr}	-	14	-	ns	I _F =-1A, V _{GS} =0V, dI _F /dt=100A/μs
*Q _{rr}	-	8	-	nC	

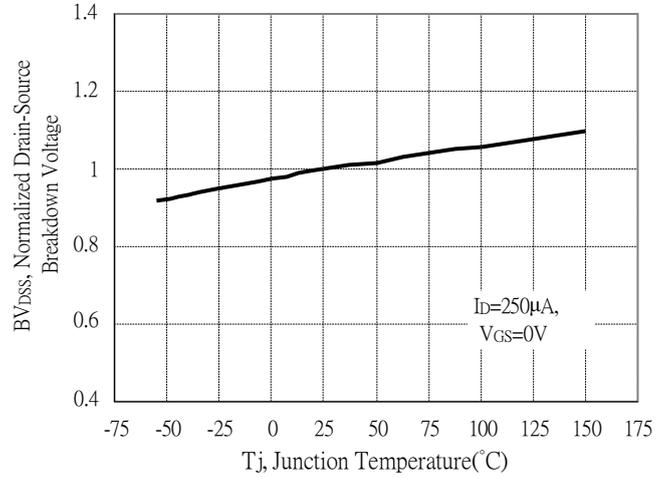
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

N-channel Typical Characteristics

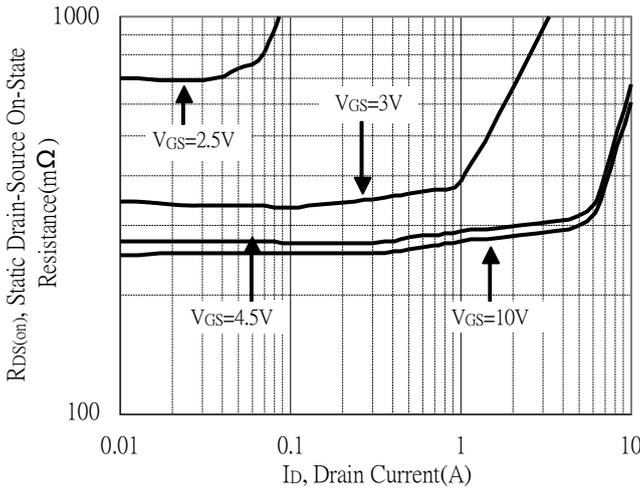
Typical Output Characteristics



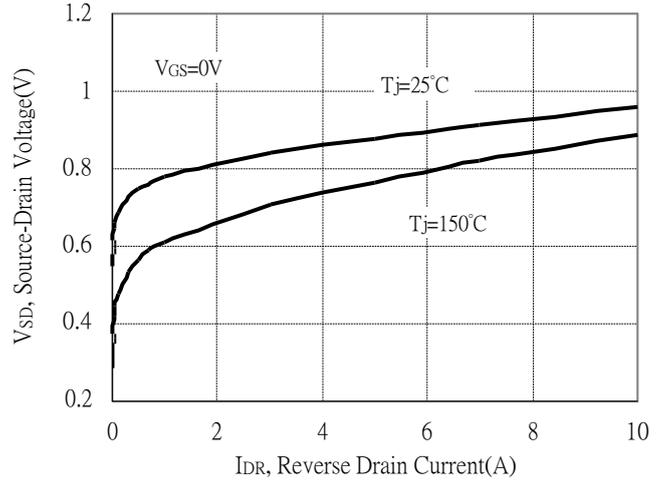
Brekdown Voltage vs Ambient Temperature



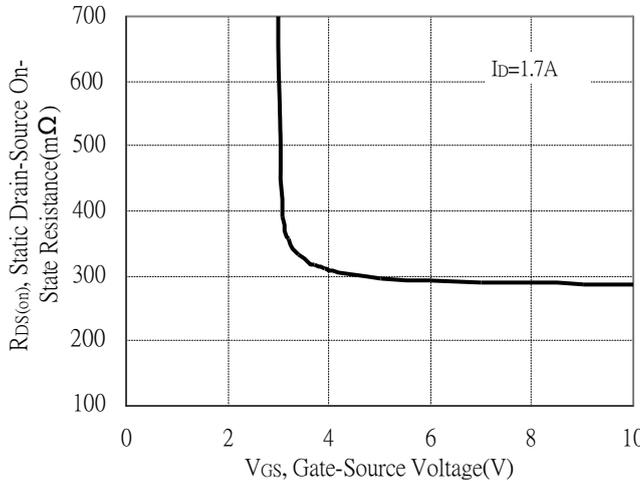
Static Drain-Source On-State resistance vs Drain Current



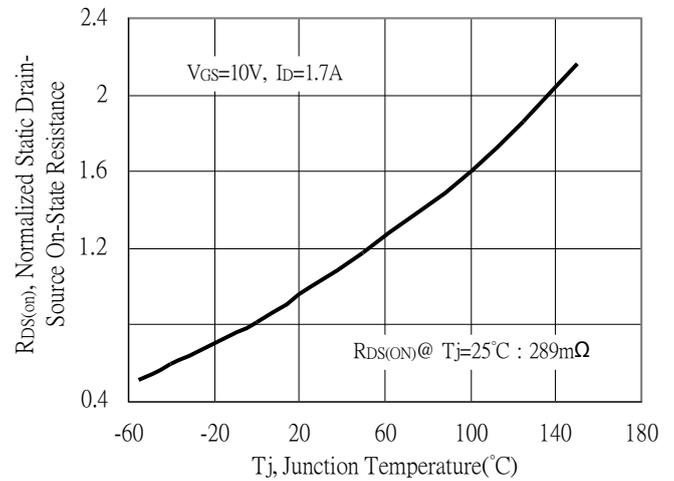
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

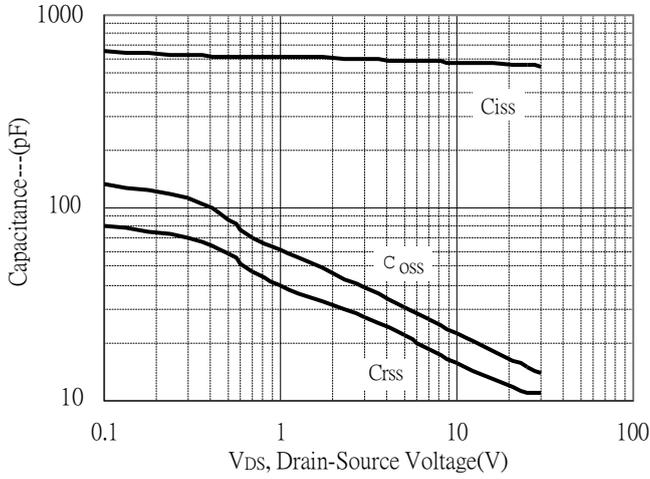


Drain-Source On-State Resistance vs Junction Temperature

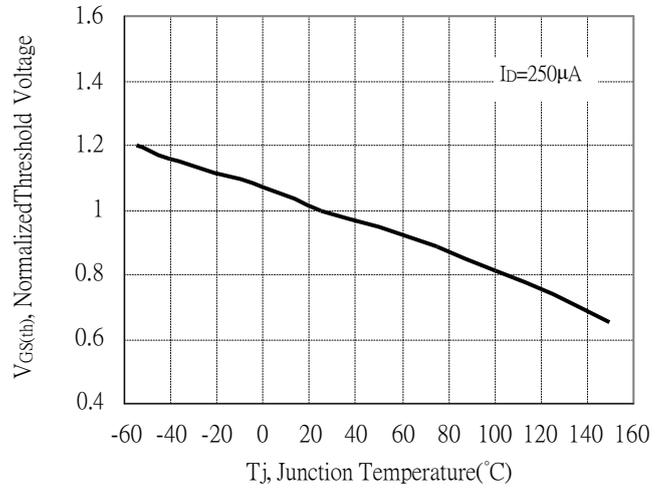


N-channel Typical Characteristics(Cont.)

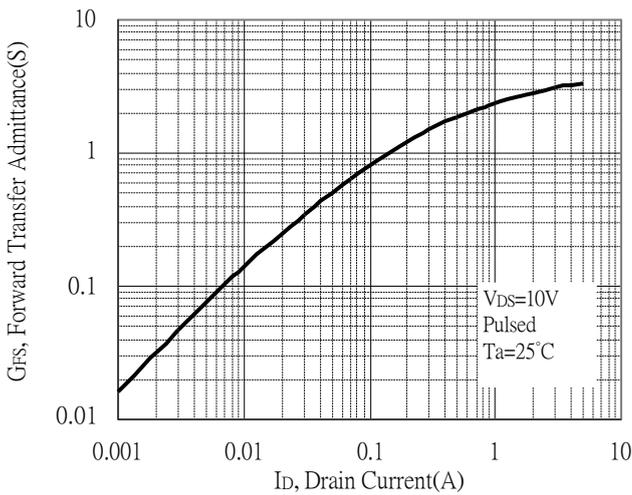
Capacitance vs Drain-to-Source Voltage



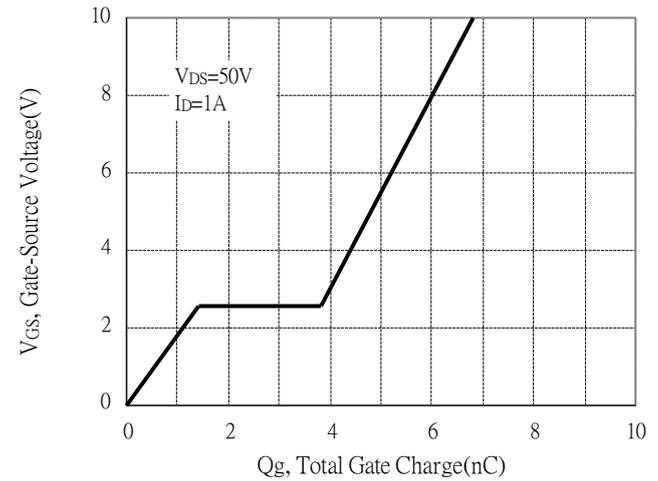
Threshold Voltage vs Junction Temperature



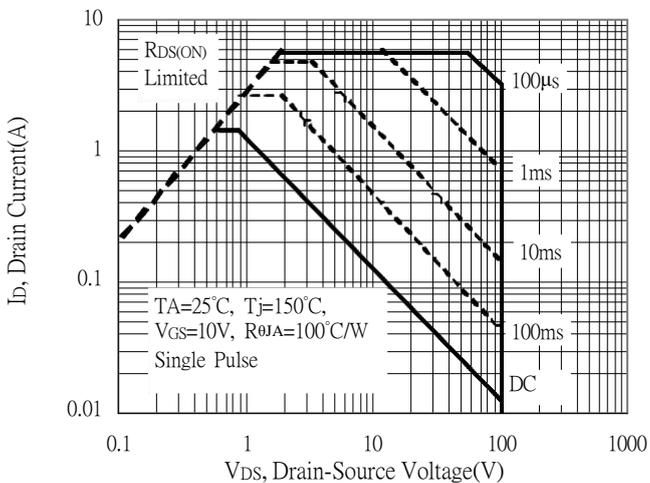
Forward Transfer Admittance vs Drain Current



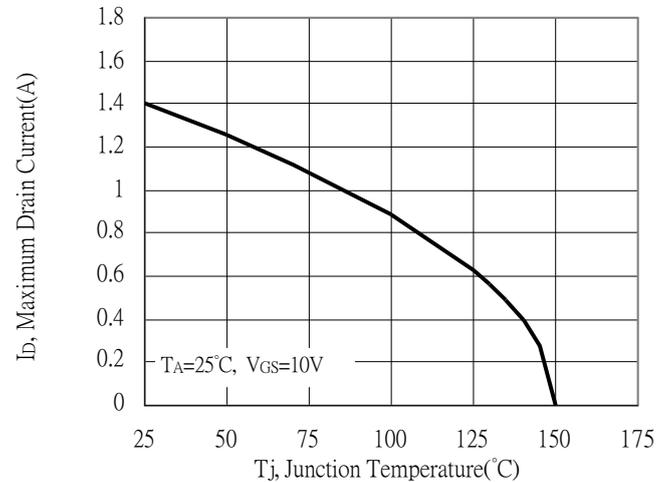
Gate Charge Characteristics



Maximum Safe Operating Area

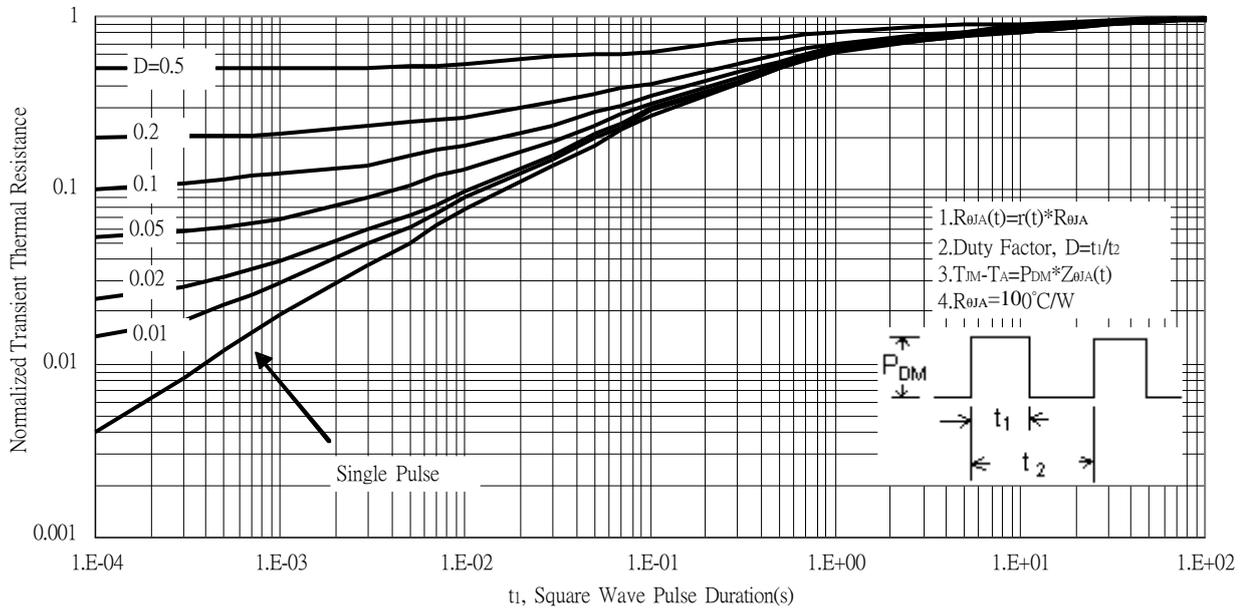


Maximum Drain Current vs Junction Temperature



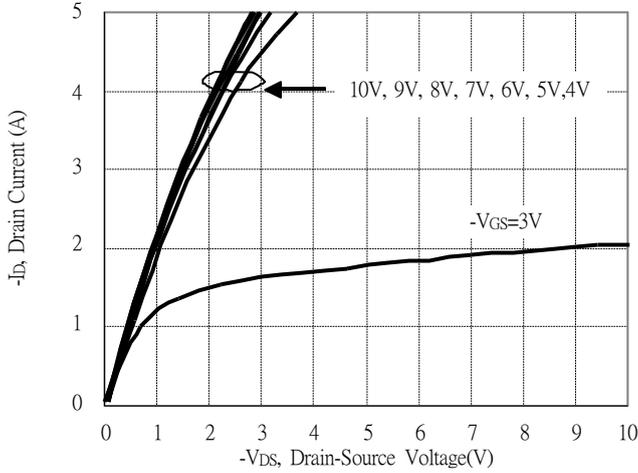
N-channel Typical Characteristics(Cont.)

Transient Thermal Response Curves

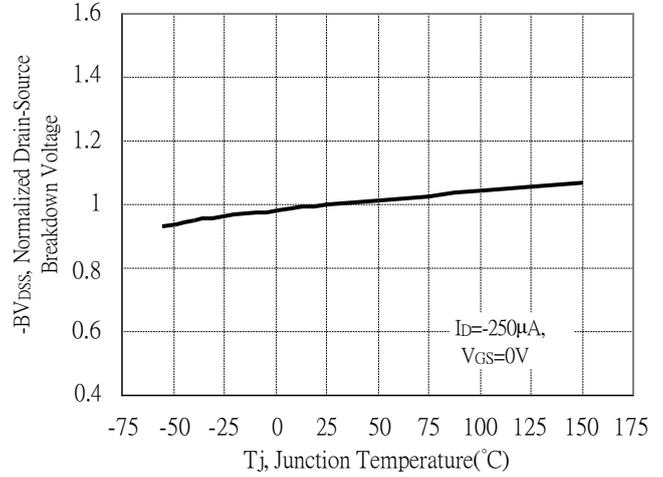


P-channel Typical Characteristics

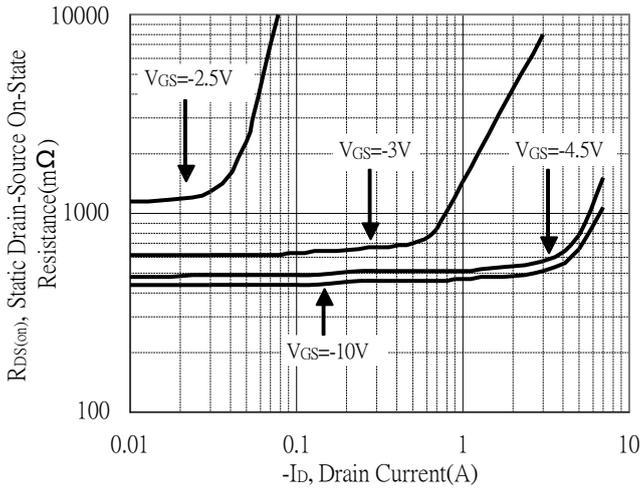
Typical Output Characteristics



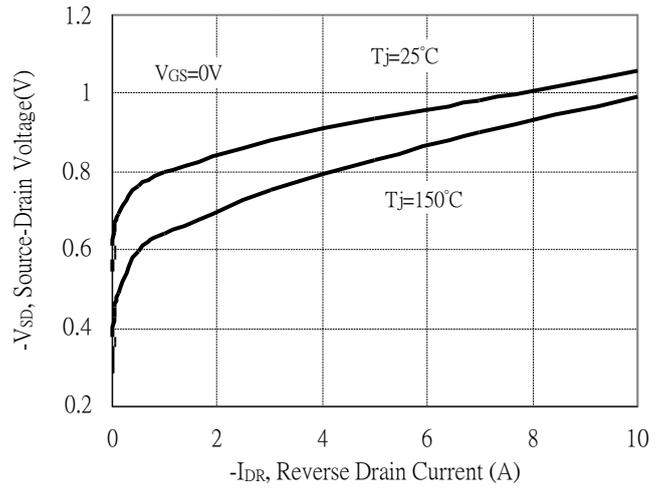
Brekdown Voltage vs Ambient Temperature



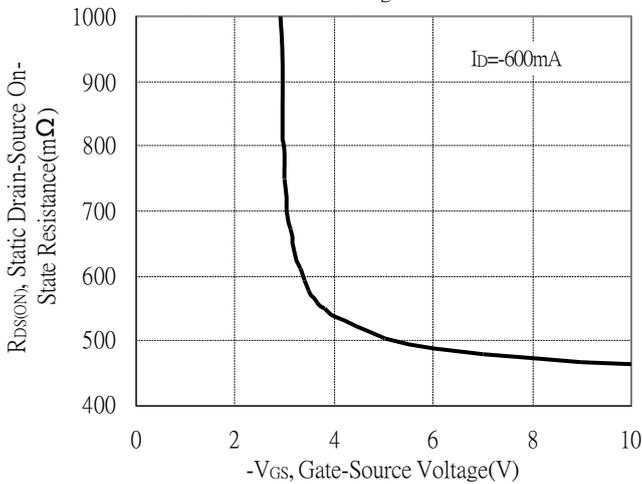
Static Drain-Source On-State resistance vs Drain Current



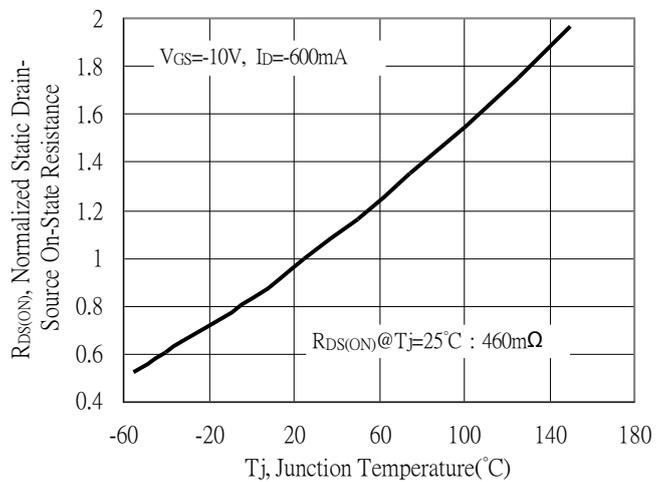
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

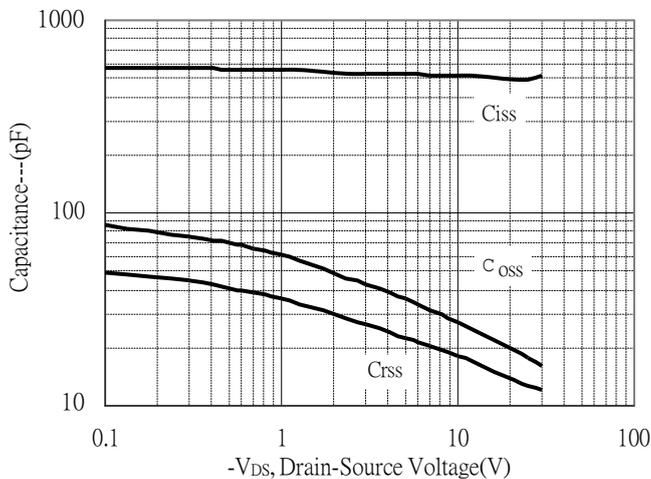


Drain-Source On-State Resistance vs Junction Temperature

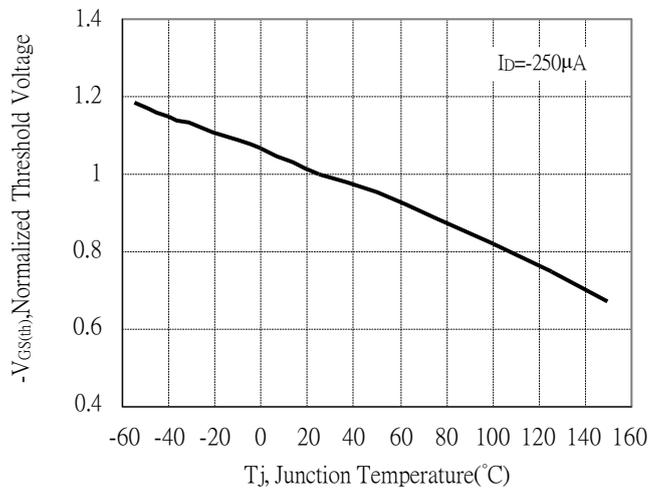


P-channel Typical Characteristics(Cont.)

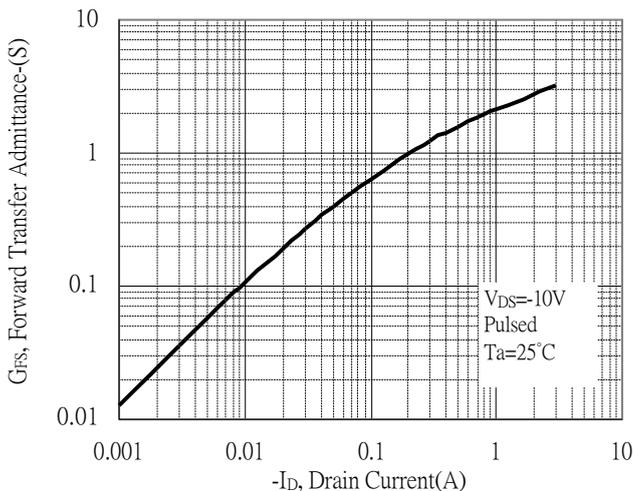
Capacitance vs Drain-to-Source Voltage



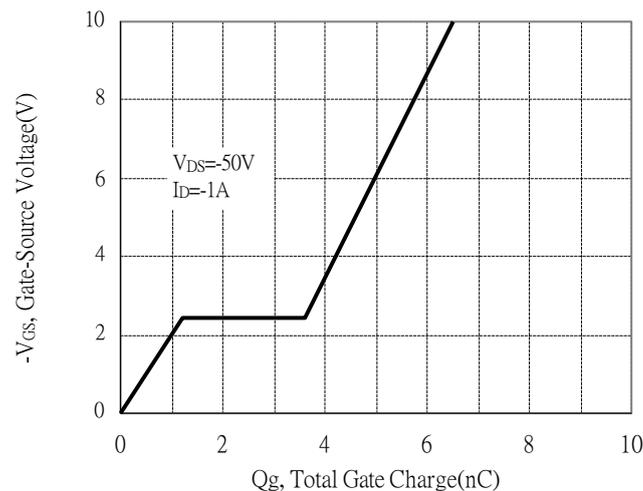
Threshold Voltage vs Junction Temperature



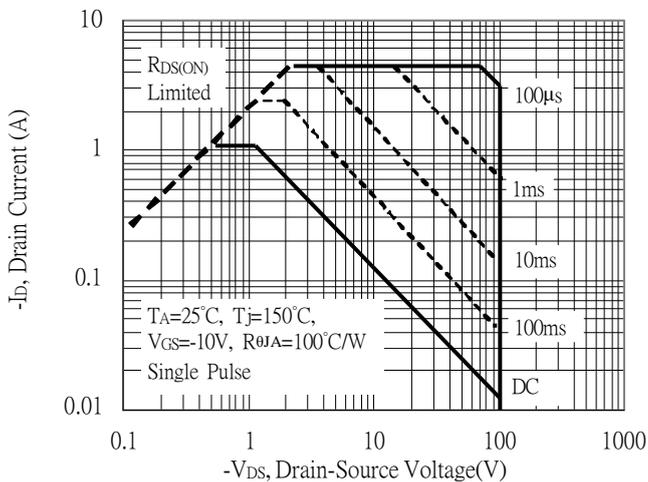
Forward Transfer Admittance vs Drain Current



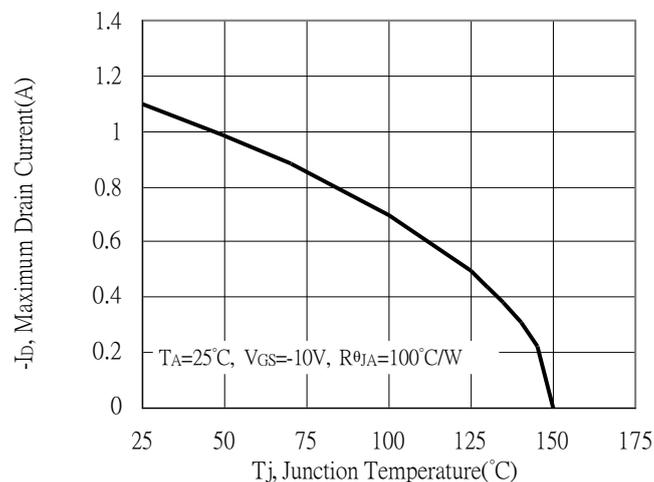
Gate Charge Characteristics



Maximum Safe Operating Area

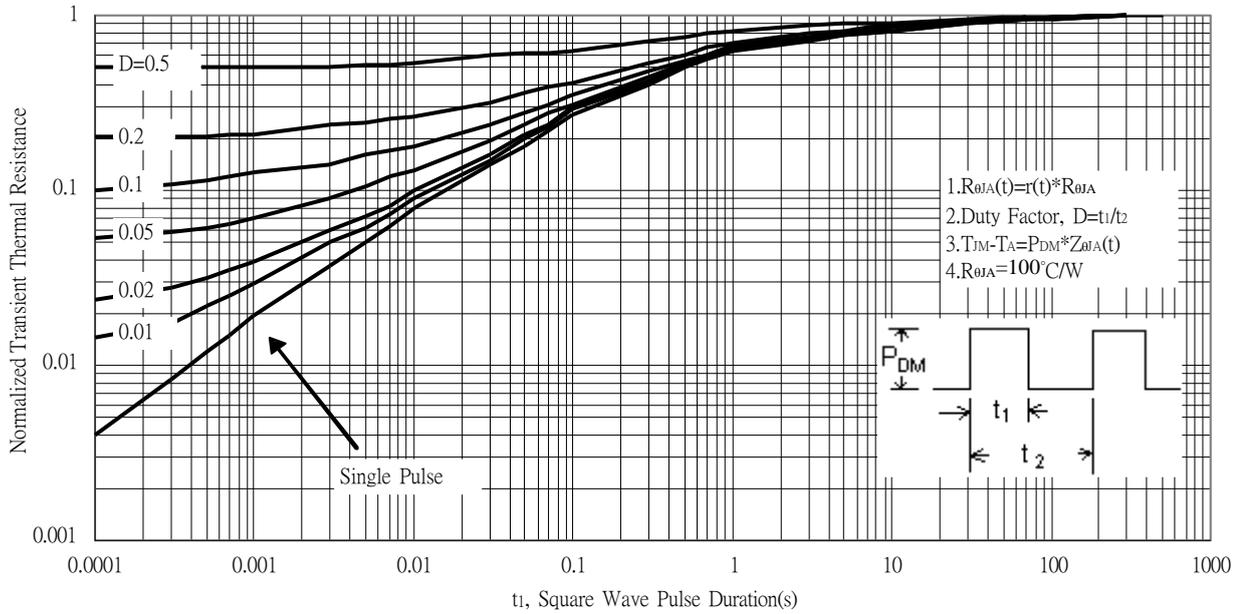


Maximum Drain Current vs Junction Temperature

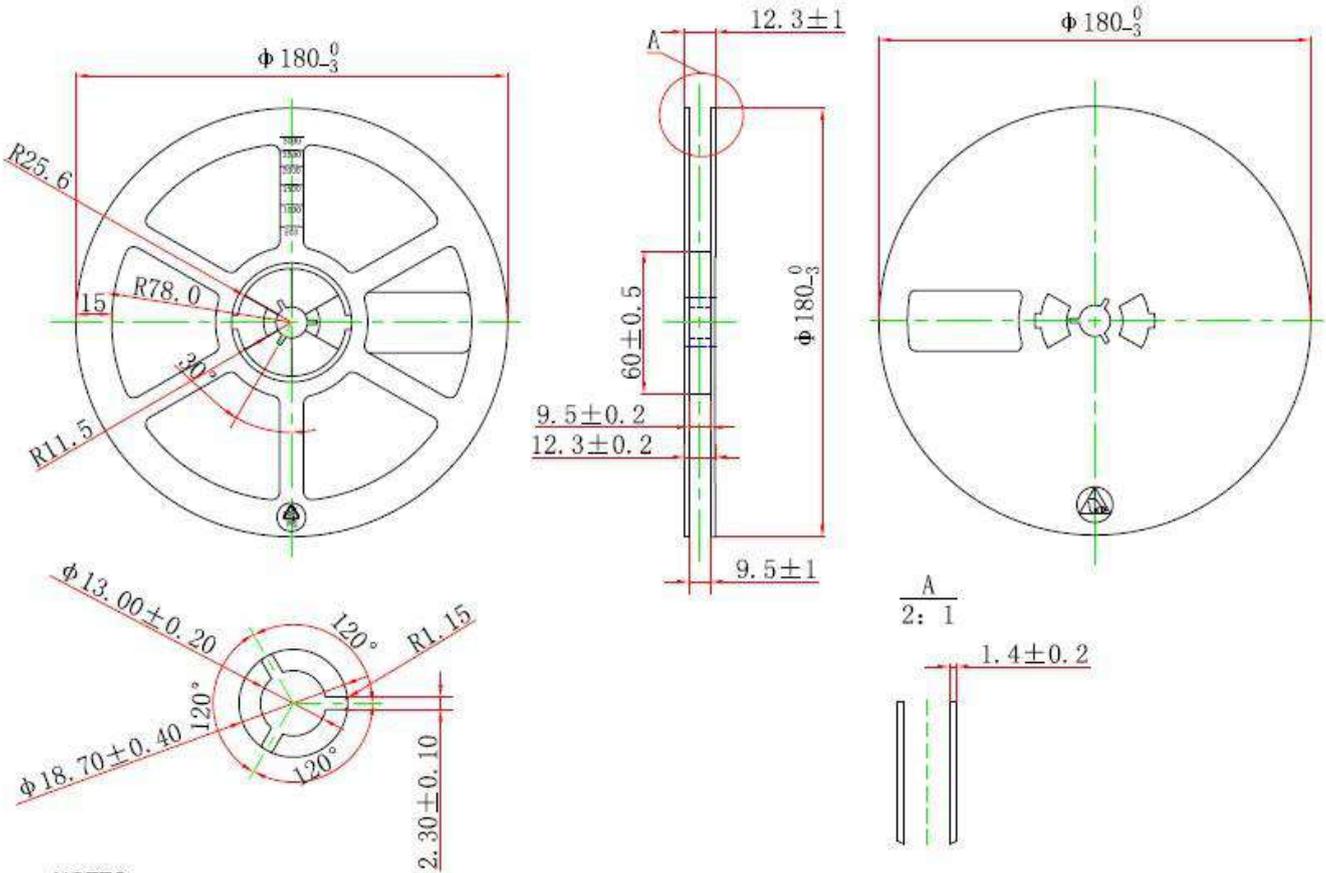


P-channel Typical Characteristics(Cont.)

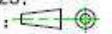
Transient Thermal Response Curves



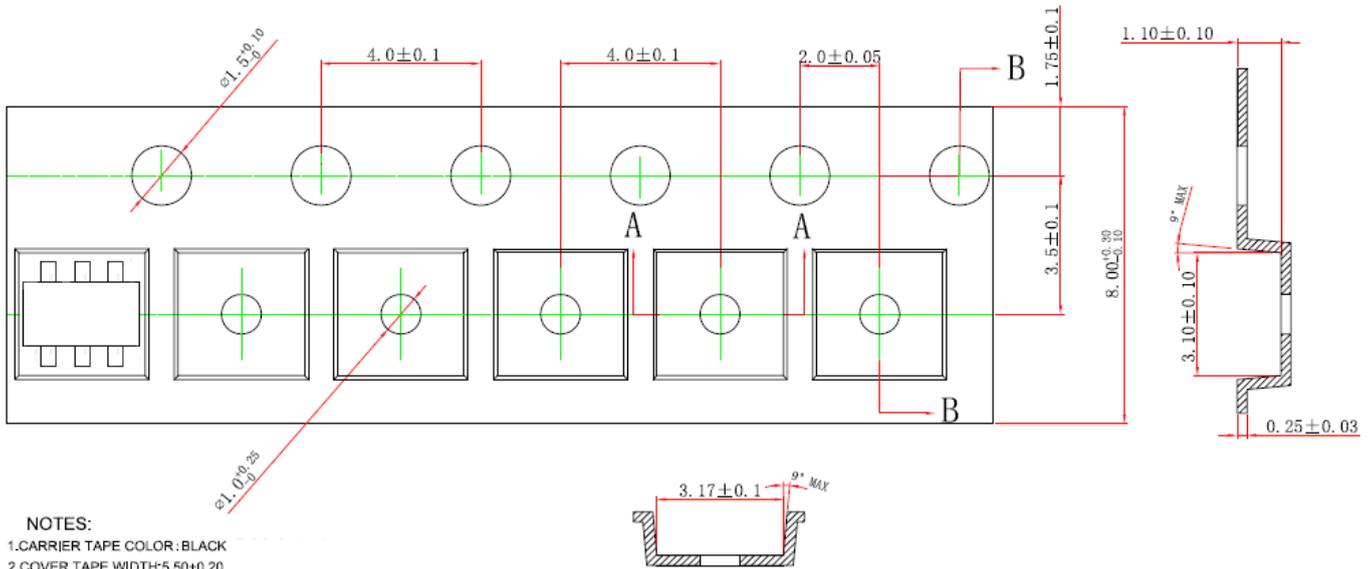
Reel Dimension



NOTES:

1. ALL DIM IN mm
2. ESD-SURFACE RESISTIVITY $10^5 \sim 10^{11}$ OHMS/SQ
3. GENERAL TOLERANCE ± 0.25 ;
4. THE DIRECTION OF VIEW : 

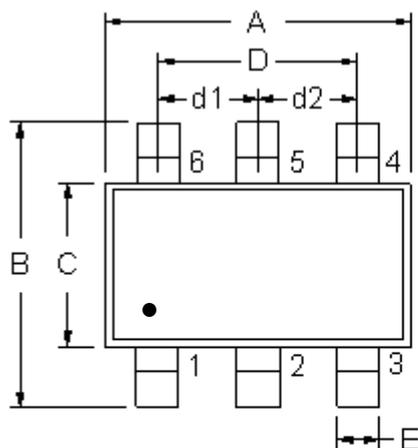
Carrier Tape Dimension



NOTES:

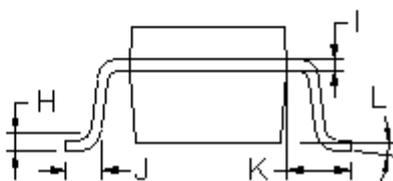
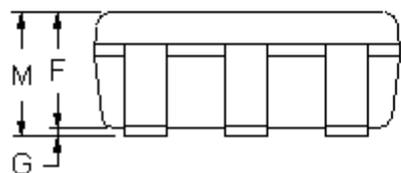
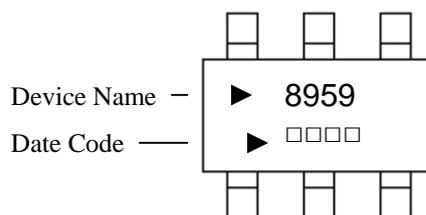
1. CARRIER TAPE COLOR: BLACK
2. COVER TAPE WIDTH: 5.50 ± 0.20
3. COVER TAPE COLOR: TRANSPARENT
5. ANTISTATIC COATED $10^9 \sim 10^{11}$ OHMS/SQ.
6. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE $\pm 0.20 \text{ MAX}$.
7. CAMBER NOT TO EXCEED 1 MM IN 100 MM
8. ALL DIMS IN mm.
9. THE DIRECTION OF VIEW: 

TSOP-6 Dimension



Style:
 Pin 1. Gate1 (G1)
 Pin 2. Source2 (S2)
 Pin 3. Gate2 (G2)
 Pin 4. Drain2 (D2)
 Pin 5. Source1 (S1)
 Pin 6. Drain1 (D1)

Marking:



6-Lead TSOP-6 Plastic
 Surface Mounted Package
 Package Code: G6

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1063	0.1220	2.70	3.10	G	0	0.0039	0	0.10
B	0.1024	0.1181	2.60	3.00	H	-	0.0098	-	0.25
C	0.0551	0.0709	1.40	1.80	I	0.0047 REF		0.12 REF	
D	0.0748 REF		1.90 REF		J	0.0177 REF		0.45 REF	
d1	0.0374 REF		0.95 REF		K	0.0236 REF		0.60 REF	
d2	0.0374 REF		0.95 REF		L	0°	10°	0°	10°
E	0.0118	0.0197	0.30	0.50	M	-	0.0433	-	1.10
F	0.0276	0.0394	0.70	1.00					